### 501781486 01/10/2012

# PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Toshinao Nakahara	01/10/2012

## **RECEIVING PARTY DATA**

Name:	NGK INSULATORS, LTD.	
Street Address:	2-56, Suda-cho, Mizuho-ku, Nagoya-city	
City:	Aichi-prefecture	
State/Country:	JAPAN	
Postal Code:	467-8530	

## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13331125

#### **CORRESPONDENCE DATA**

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ATTORNEY DOCKET NUMBER: 1027-0015

NAME OF SUBMITTER: Christopher Goode

Total Attachments: 1

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PATENT REEL: 027509 FRAME: 0302 OP \$40.00 13331125

JOINT/SOLE INVENTION

#### ASSIGNMENT

WHEREAS I/WE, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

Composite Substrate and Method for Manufacturing the Composite Substrate

for which I/WE executed an application for United States Letters Patent concurrently herewith; and

WHEREAS <u>NGK INSULATORS, LTD.</u>, a corporation of <u>Japan</u>, whose post office address is <u>2-56</u>, <u>Suda-cho</u>, <u>Mizuho-ku</u>, <u>Nagoya-city</u>, <u>Aichi-prefecture 467-8530</u>, <u>Japan</u> (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application of United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for and in consideration of the sum of One Dollar (\$1.00) in hand paid and other good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such applications, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and WE/I hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent of this invention to Assignce, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY covenant that I/WE have the full right to convey the interest assigned by this Assignment, and I/WE have not executed and will not execute any agreement in conflict with this Assignment;

AND, I/WE HERBBY further covenant and agree that I/WE will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to US respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns;

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. 13|33|,125, filed 12|20|20|1) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I have hereunto set my hand.

**RECORDED: 01/10/2012** 

Full Name of First Assignor Toshinao NAKAHARA	Assignor's Signature To Shina o Nakahara	Date /0 / 1 / 2012
Address: c/o NGK INSULATORS, LTD. 2-56, Suda-cho, Mizuho-ku, Nagoya-city, A	<u>Citizenship</u> Japan	
Names of additional invento	ors attached [ ] Yes	[X] No

PATENT
REEL: 027509 FRAME: 0303